

# EB13E2E2H-8.000M TR [Click part number to visit Part Number Details page](#)

## REGULATORY COMPLIANCE (Data Sheet downloaded on Jan 8, 2020)



◀ Click badges to download compliance docs

Regulatory Compliance standards are subject to updates by governing bodies. Click the badges to download the latest compliance docs for this part number directly from Ecliptek.



## ITEM DESCRIPTION

Quartz Crystal Clock Oscillators XO (SPXO) LVCMOS (CMOS) 3.3Vdc 4 Pad 2.5mm x 3.2mm Ceramic Surface Mount (SMD) 8.000MHz  $\pm 25$ ppm over -20°C to +70°C

## ELECTRICAL SPECIFICATIONS

Nominal Frequency	8.000MHz
Frequency Tolerance/Stability	$\pm 25$ ppm Maximum over -20°C to +70°C (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C, Shock, and Vibration)
Supply Voltage	3.3Vdc $\pm 5\%$
Input Current	3mA Maximum
Output Voltage Logic High (Voh)	90% of Vdd Minimum (IOH= -4mA)
Output Voltage Logic Low (Vol)	10% of Vdd Maximum (IOL= +4mA)
Rise/Fall Time	5nSec Maximum (Measured at 20% to 80% of waveform)
Duty Cycle	50 $\pm 5$ (%) (Measured at 50% of waveform)
Load Drive Capability	15pF Maximum
Output Logic Type	CMOS
Pin 1 Connection	Tri-State (High Impedance)
Tri-State Input Voltage (Vih and Vil)	80% of Vdd Minimum or No Connect to Enable Output, 20% of Vdd Maximum to Disable Output (High Impedance)
Standby Current	10 $\mu$ A Maximum (Disabled Output: High Impedance)
RMS Phase Jitter	1pSec Maximum (Fj = 12kHz to 20MHz)
Start Up Time	10mSec Maximum
Storage Temperature Range	-55°C to +125°C

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Flammability	UL94-V0
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A

## EB13E2E2H-8.000M TR [Click part number to visit Part Number Details page](#)

### MECHANICAL DIMENSIONS (all dimensions in millimeters)



PIN	CONNECTION
1	Tri-State
2	Case/Ground
3	Output
4	Supply Voltage

LINE	MARKING
1	<b>E8.00</b> E=Ecliptek Designator
2	<b>XXXXX</b> XXXXX=Ecliptek Manufacturing Identifier

### Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are  $\pm 0.1$

# EB13E2E2H-8.000M TR [Click part number to visit Part Number Details page](#)

## OUTPUT WAVEFORM & TIMING DIAGRAM



# EB13E2E2H-8.000M TR [Click part number to visit Part Number Details page](#)

## Test Circuit for CMOS Output



Note 1: An external 0.01µF ceramic bypass capacitor in parallel with a 0.1µF high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value C<sub>L</sub> includes sum of all probe and fixture capacitance.

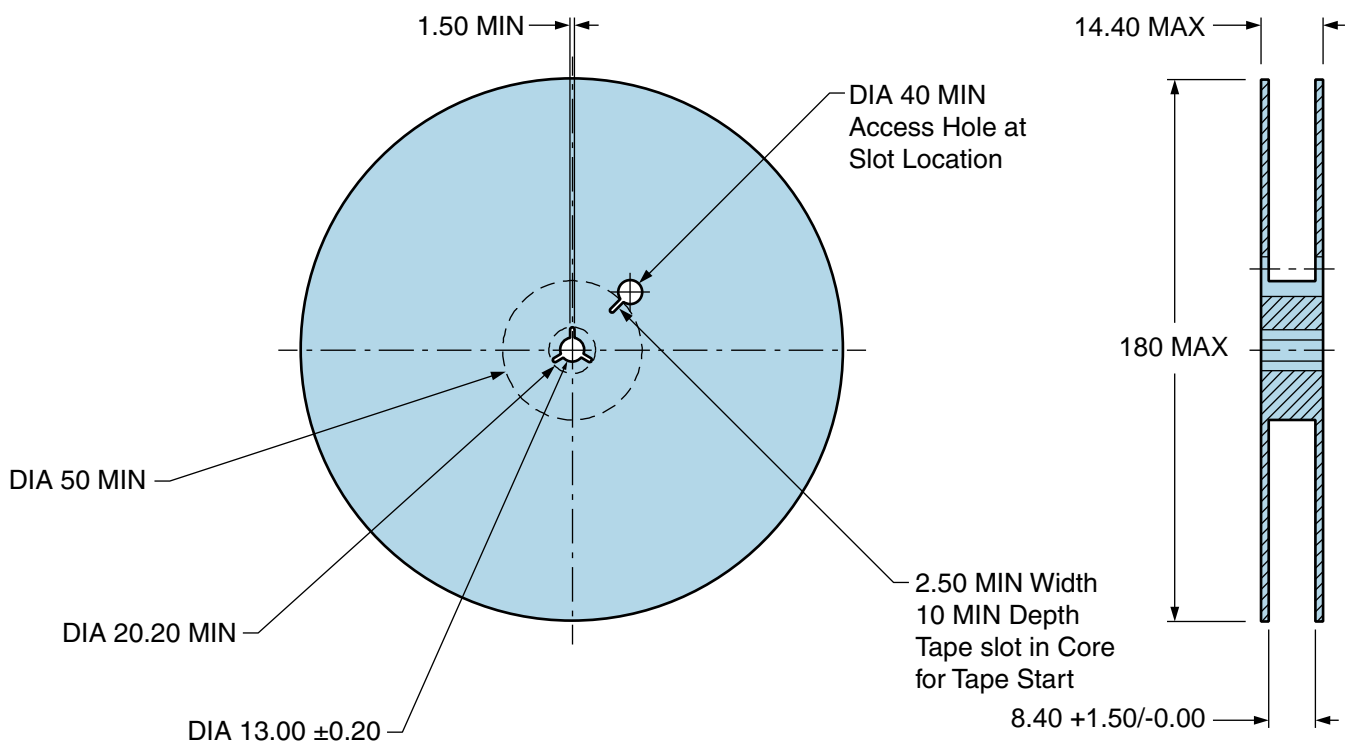
# EB13E2E2H-8.000M TR

## Tape & Reel Dimensions

Quantity Per Reel: 1,000 units

All Dimensions in Millimeters

Compliant to EIA-481



# EB13E2E2H-8.000M TR [Click part number to visit Part Number Details page](#)

## Recommended Solder Reflow Methods



### High Temperature Infrared/Convection

Ts MAX to Tl (Ramp-up Rate)	3°C/Second Maximum
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#### Preheat

- Temperature Minimum (Ts MIN)	150°C
- Temperature Typical (Ts TYP)	175°C
- Temperature Maximum (Ts MAX)	200°C
- Time (ts MIN)	60 - 180 Seconds

Ramp-up Rate (Tl to Tp)	3°C/Second Maximum
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#### Time Maintained Above:

- Temperature (Tl)	217°C
- Time (tL)	60 - 150 Seconds

Peak Temperature (Tp)	260°C Maximum for 10 Seconds Maximum
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Target Peak Temperature (Tp Target)	250°C +0/-5°C
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Time within 5°C of actual peak (tp)	20 - 40 Seconds
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Ramp-down Rate	6°C/Second Maximum
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Time 25°C to Peak Temperature (t)	8 Minutes Maximum
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Moisture Sensitivity Level	Level 1
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# EB13E2E2H-8.000M TR [Click part number to visit Part Number Details page](#)

## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 240°C

Ts MAX to Tl (Ramp-up Rate)	5°C/Second Maximum
<b>Preheat</b>	
- Temperature Minimum (Ts MIN)	N/A
- Temperature Typical (Ts TYP)	150°C
- Temperature Maximum (Ts MAX)	N/A
- Time (ts MIN)	60 - 120 Seconds
<b>Ramp-up Rate (Tl to Tp)</b>	5°C/Second Maximum
<b>Time Maintained Above:</b>	
- Temperature (Tl)	150°C
- Time (tL)	200 Seconds Maximum
<b>Peak Temperature (Tp)</b>	240°C Maximum
<b>Target Peak Temperature (Tp Target)</b>	240°C Maximum 2 Times / 230°C Maximum 1 Time
<b>Time within 5°C of actual peak (tp)</b>	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
<b>Ramp-down Rate</b>	5°C/Second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	N/A
<b>Moisture Sensitivity Level</b>	Level 1

### Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum.

### High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum.